

**Sandwich-structured intelligent power module for building into appliances includes a printed circuit board for a logical unit with a recess fitted with a power substrate on a cooling plate connected by a wire bonding technique.**

Patent Number: DE19924994

Publication date: 2000-12-21

Inventor(s): FRISCH MICHAEL (DE)

Applicant(s): TYCO ELECTRONICS LOGISTICS AG (CH)

Requested Patent:  DE19924994

Application Number: DE19991024994 19990531

Priority Number(s): DE19991024994 19990531

IPC Classification: H05K1/14; H05K3/34

EC Classification: H01L25/16F, H01L25/16H, H05K1/14C, H05K1/18F

Equivalents:

---

**Abstract**

---

A printed circuit board (5) for a logical unit has a recess (6) fitted with a power substrate (2) on a cooling plate (8) and connected electrically to the logical unit by means of a wire bonding technique. A power unit's components (1) including power semiconductors fit on the power substrate. The logical unit's IC and SMD components (3,4) fit on the printed circuit board.

Data supplied from the esp@cenet database - I2